



103037893

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof

1. Name of conveying party(ies):

Yang Gu KANG; Seung Heon LEE; Young Jun HONG;
Jung Hoon KIM; Hye Jeong LEE; Sang Ho SHIN; Sung
Hoon JANG; Yeong Rae CHANG; Hong Cheul SHIN;
Yeon Bin LEE

Additional name(s) of conveying party(ies)
attached? ☐ Yes ☒ No

3. Nature of Conveyance:

☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other _____

Execution Date: June 9, 2005

2. Name and address of receiving party(ies)

Name: LG Chem, Ltd.

Internal Address: _____

Street Address: _____

20, Yoido-dong, Youngdungpo-gu
Seoul 150-721
REPUBLIC OF KOREA

City: _____

State: _____

Zip: _____

Additional name(s) &
address(es) attached: ☐ Yes ☒ No

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the new application is: June 9, 2005

A. Patent Application No.(s):

This application

B. Patent No.(s):

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence
concerning document should be mailed:

Name: Song K. Jung
MCKENNA LONG & ALDRIDGE LLP
Internal Address: Atty. Dkt.: 29137.079.00-US
Street Address:
1900 K Street, N.W.

City: Washington State: DC Zip: 20006

6. Total number of applications and
patents involved: 1

7. Total fee (37 CFR 3.41) \$ 40.00
☒ Enclosed
☐ Authorized to be charged to deposit account
☐ Authorized to be charged to credit card
(Form 2038 enclosed)

8. Deposit account number:

50-0911

(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy
is a true copy of the original document.

Song K. Jung, Reg. No. 35,210
Name of Person Signing

Signature

Reg. No. 42,766 Date July 1, 2005

Total number of pages including cover sheet, attachments, and documents: 3

07/06/2005 EHAILE1 00000069 11171326

04 FC:8021

40.00 DP

DC:50338971.1

PATENT
REEL: 016713 FRAME: 0526

Assignment of Application

WHEREAS, I (WE)	Yang Gu KANG, Seung Heon LEE, Young Jun HONG,		
	Jung Hoon KIM, Hye Jeong LEE , Sang Ho SHIN, Sung Hoon JANG,		
	Yeong Rae CHANG , Hong Cheul SHIN, Yeon Bin LEE;	, respectively,	
have invented certain new and useful improvements in:			
FILMS OR STRUCTURAL EXTERIOR MATERIALS USING COATING COMPOSITION HAVING SELF-CLEANING PROPERTY AND PREPARATION METHOD THEREOF			
for which an application for Letters Patent was executed on			

(Application No.		, Filed		), and
WHEREAS,	LG CHEM, LTD.			
(hereinafter referred to as "ASSIGNEE") having a place of business at: 20, Yoido-dong, Youngdungpo-gu, Seoul 150-721, Republic of Korea				

is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent that may be granted therefore in the United States and its territorial possessions and in any and all foreign countries;

NOW, THEREFORE, in consideration of the sum of FIVE DOLLARS (\$5.00), the receipt whereof is hereby acknowledged, and for other good and valuable consideration, I (WE), by these presents do sell, assign and transfer unto said ASSIGNEE, the full and exclusive right to the said invention in the United States and its territorial possessions and in all foreign countries and the entire right, title and interest in and to any and all Letters patent which may be granted therefor in the United States and its territorial possessions and in any and all foreign countries and in and to any and all divisions, reissues, continuations, substitutions and renewals thereof.

I (WE) hereby authorize and request the Patent Office Officials in the United States and Its territorial possessions and any and all foreign countries to issue any and all of said Letters Patent, when granted, to said ASSIGNEE as the assignee of my (our) entire right, title and interest in and to the same, for the sole use and behalf of said ASSIGNEE, its (his) successors and assigns, to the full end of the term for which said Letters Patent may be granted, as fully and entirely as the same would have been held by me (us) had this Assignment and sale not been made.

Further, I (WE) agree that I (WE) will communicate to said ASSIGNEE or its (his) representatives any facts known to me (us) respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitute, renewal and reissue applications, execute all necessary assignment papers to cause any and all of said Letters Patent to be issued to said ASSIGNEE, make all rightful oaths, and, generally do everything possible to aid said ASSIGNEE, its (his) successors and assigns, to obtain and

enforce proper protection for said invention in the United States and its territorial possessions and in any and all foreign countries.

The undersigned hereby grant(s) the firm of McKenna Long & Aldridge LLP, Attorneys at Law, 1900 K Street, N.W., Washington, D.C. 20006 the power to insert on this assignment any further identification, including the application number and filing date, which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

Date: 6.9.2005

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(Signature of Inventor)
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Date: 6.9.2005

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Seung Heon LEE

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